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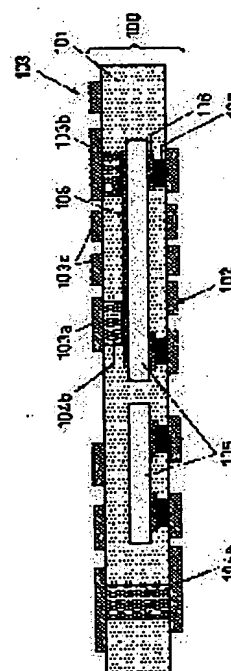
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## (54) CIRCUIT BOARD AND METHOD OF PRODUCTION

## (57)Abstract:

PROBLEM TO BE SOLVED: To provide a circuit board in which high density mounting can be effected without lowering the containing rate of wiring.

SOLUTION: Containing rate of wiring is enhanced by forming an auxiliary wiring pattern 108 in a component surface region not pertaining to external connection of an electronic component 105 provided in a board, and connecting the auxiliary wiring pattern 108 electrically with wiring patterns of board 103, 102 thereby using the auxiliary wiring pattern 108 as the wiring patterns of board 103, 102.



## LEGAL STATUS

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